Abstracts

The thermal benefits of diamond enhanced plastic packages for microwave applications

M. Gomes-Casseres. "The thermal benefits of diamond enhanced plastic packages for microwave applications." 1998 MTT-S International Microwave Symposium Digest 98.2 (1998 Vol. II [MWSYM]): 1099-1102.

The superior material properties of diamond combined with the economics of plastic packaging provide the ultimate thermal management solution. A GaAs power amplifier dissipating 20 W has been demonstrated in a diamond enhanced plastic package. In addition, a dramatic improvement in the electrical performance of a coplanar flip chip MMIC in plastic has been achieved.

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